

DUAL P-CHANNEL ENHANCEMENT MODE MOSFET
Product Summary

BV_{D1D2}	R_{D1D2(ON)}	I_{D1D2} T_C = +25°C
-20V	100mΩ @ V _{GS} = -4.5V	-4.0 A

Description

This new generation MOSFET has been designed to minimize the on-state resistance (R_{D1D2(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

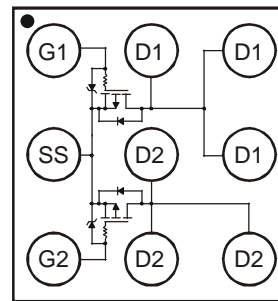
- Battery Management
- Load Switch
- Battery Protection


Features and Benefits

- Low Q_g & Q_{gd}
- Dual PMOS in Common-Source Configuration
- Small Footprint 1.5-mm x 1.5-mm
- **Gate ESD Protection to 3kV**
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: U-WLB1515-9
- Terminal Connections: See Diagram Below
- Weight: 0.0018 grams (approximate)

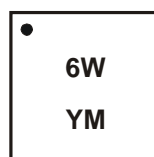


Top View

Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2100UCB9-7	U-WLB1515-9	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


6W = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: Y = 2011)
 M = Month (ex: 9 = September)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{D1D2}	-20	V
Gate-Source Voltage			V _{GS}	-6	V
Continuous Drain Current (Note 5) V _{GS} = -4.5V	Steady State	T _C = +25°C	I _{D1D2}	-3.0	A
		T _C = +70°C		-2.1	
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Steady State	T _C = +25°C	I _{D1D2}	-4.0	A
		T _C = +70°C		-3.0	
Continuous Source Pin Current (Note 6)			I _S	-2.0	A
Continuous Gate Clamp Current (Note 6)			I _G	-0.4	A
Pulsed Source Pin Current (Pulse duration 10μs, duty cycle ≤ 1%)			I _{SM}	-15	A
Pulsed Drain Current (Pulse duration 10μs, duty cycle ≤ 1%)			I _{DM}	-28	A
Pulsed Gate Clamp Current (Pulse duration 10μs, duty cycle ≤ 1%)			I _{GM}	-6	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P _D	0.8	W
Total Power Dissipation (Note 6)	P _D	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	152	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	65	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{D1D2}	-20	—	—	V	V _{GS} = 0V, I _{D1D2} = -250μA
Gate-Source Breakdown Voltage	BV _{GS}	-6.1	—	—	V	I _{GS} = -250μA, V _{D1D2} = 0V
Zero Gate Voltage Drain Current @T _C = +25°C	I _{DD}	—	—	-1	μA	V _{D1D2} = -16V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	-100	nA	V _{GS} = -6V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	-0.4	-0.7	-0.9	V	V _{D1D2} = V _{GS} , I _{DS} = -250μA
Static Drain-Source On-Resistance	R _{D1D2(ON)}	—	80	100	mΩ	V _{GS} = -4.5V, I _{D1D2} = -1A
		—	105	130		V _{GS} = -2.5V, I _{D1D2} = -1A
		—	140	175		V _{GS} = -1.8V, I _{D1D2} = -1A
Forward Transfer Admittance	Y _{fs}	—	5.3	—	S	V _{D1D2} = -10V, I _{D1D2} = -1A
DIODE CHARACTERISTICS						
Diode Forward Voltage (Note 6)	V _{SD}	—	-0.7	-1	V	V _{GS} = 0V, I _{D1D2} = -1A
Reverse Recovery Charge	Q _{rr}	—	18	—	nC	V _{dd} = -9.5V, I _F = -1A,
Reverse Recovery Time	t _{rr}	—	34	—	ns	di/dt = 200A/μs
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	232	310	pF	V _{D1D2} = -10V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	107	150	pF	
Reverse Transfer Capacitance	C _{rss}	—	43.5	55	pF	
Total Gate Charge (4.5V)	Q _g	—	3.3	4.2	nC	V _{GS} = -4.5V, V _{D1D2} = -10V, I _{D1D2} = -1A
Gate-Source Charge	Q _{gs}	—	0.3	—	nC	
Gate-Drain Charge	Q _{gd}	—	0.6	—	nC	
Gate Charge at V _{th}	Q _{g(th)}	—	0.2	—	nC	
Turn-On Delay Time	t _{D(on)}	—	8.5	—	ns	V _{D1D2} = -10V, V _{GS} = -4.5V, I _{D1D2} = -1A, R _G = 30Ω,
Turn-On Rise Time	t _r	—	7.0	—	ns	
Turn-Off Delay Time	t _{D(off)}	—	47	—	ns	
Turn-Off Fall Time	t _f	—	28	—	ns	

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout.
 - Device mounted on FR4 material with 1-inch²(6.45-cm²), 2-oz. (0.071-mm thick) Cu
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

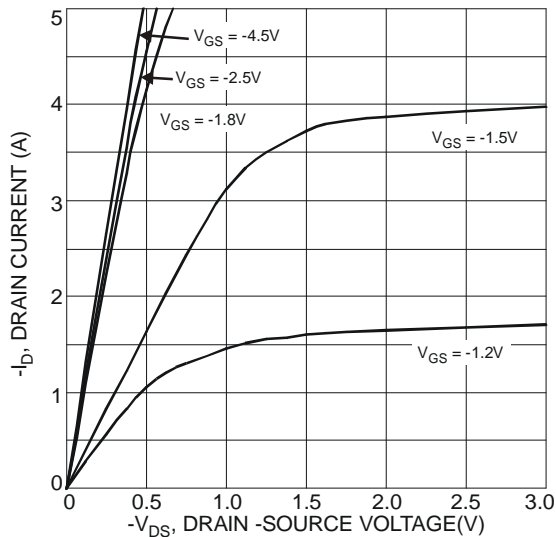


Fig. 1 Typical Output Characteristics

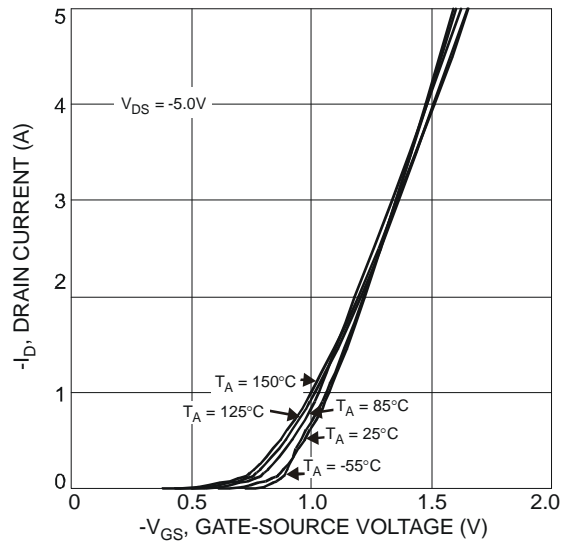


Fig. 2 Typical Transfer Characteristics

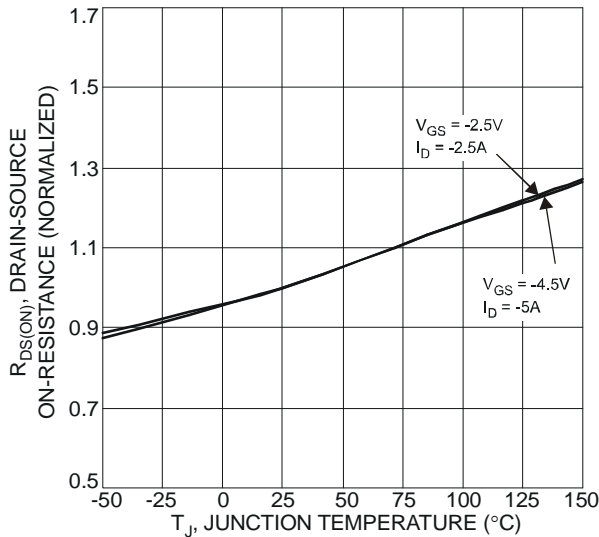


Fig. 3 On-Resistance Variation with Temperature

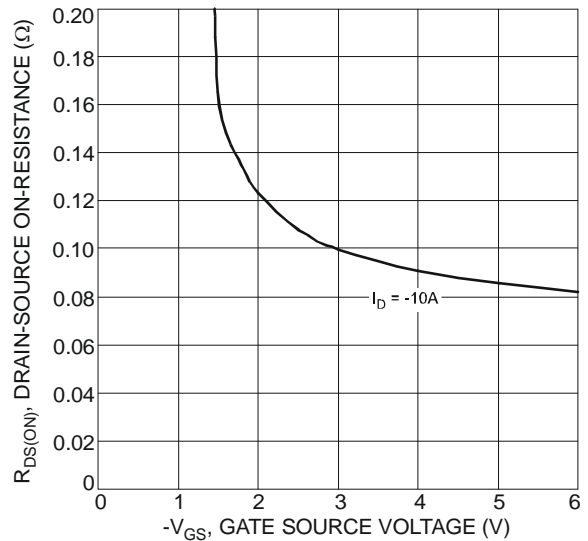


Fig. 4 Typical On-Resistance vs. Drain Current and Gate Voltage

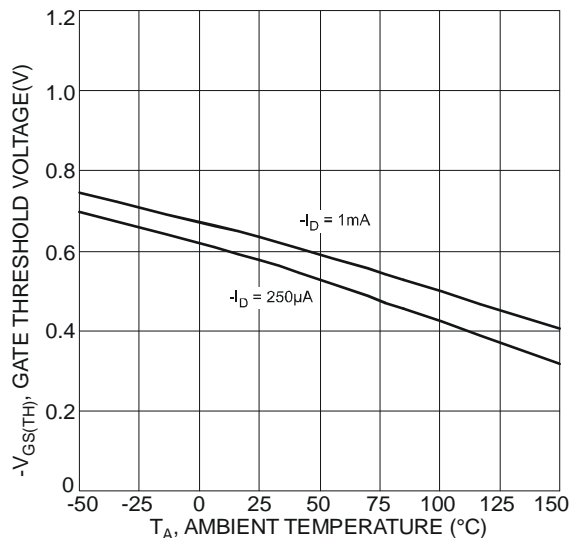


Fig. 5 Gate Threshold Variation vs. Ambient Temperature

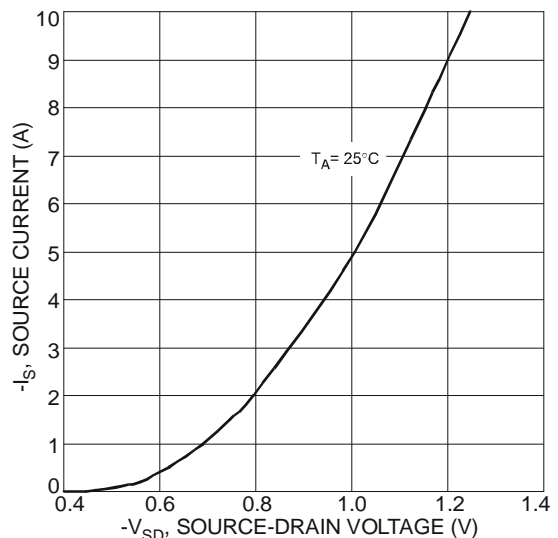


Fig. 6 Diode Forward Voltage vs. Current

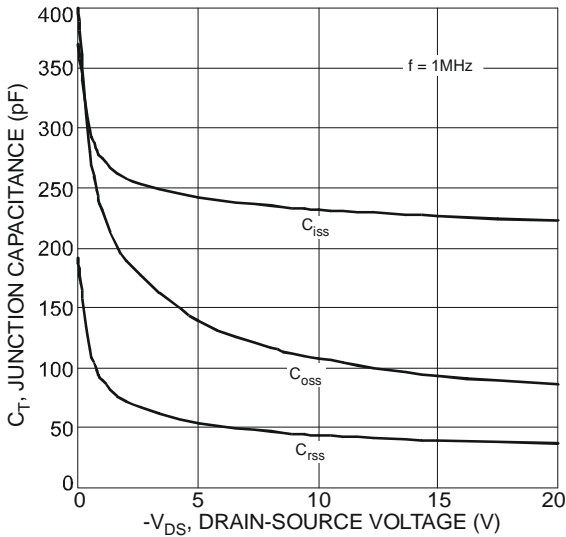


Fig. 7 Typical Junction Capacitance

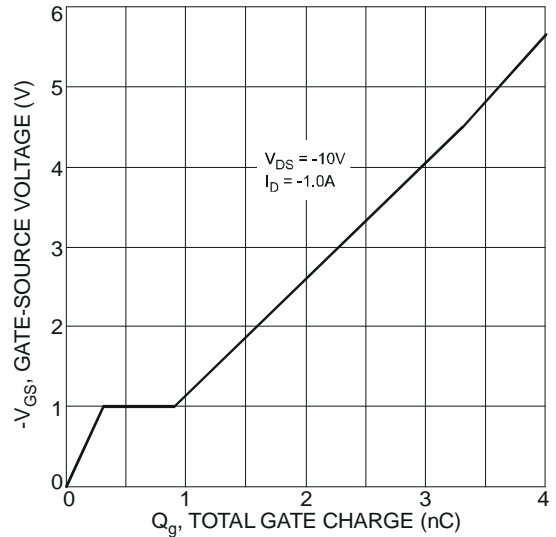


Fig. 8 Gate-Charge Characteristics

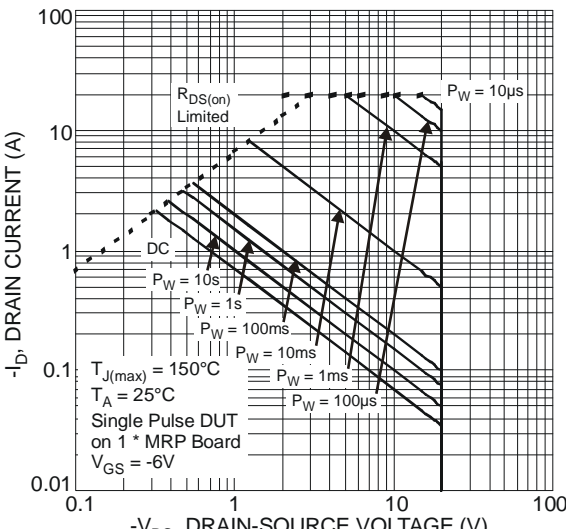


Fig. 9 SOA, Safe Operation Area

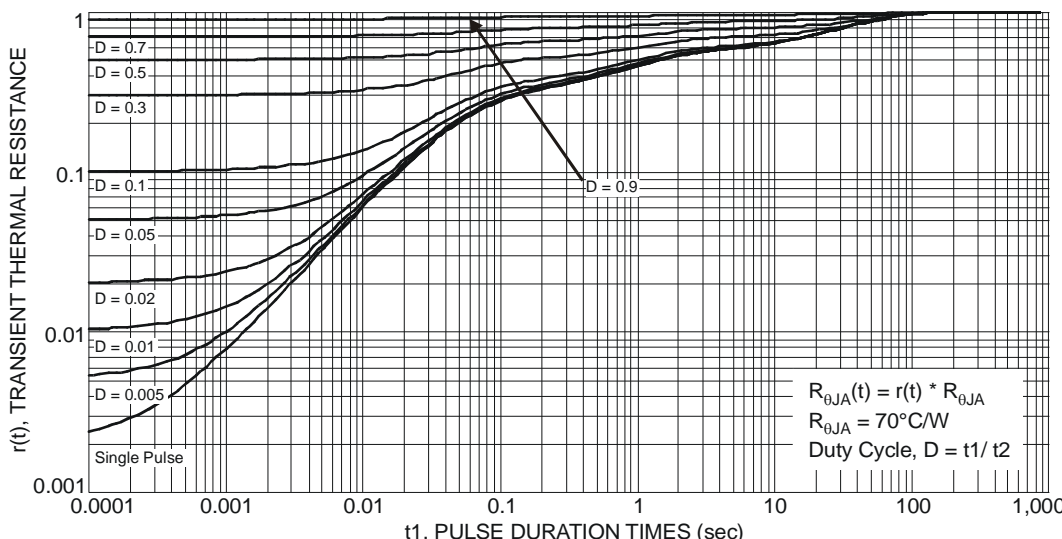
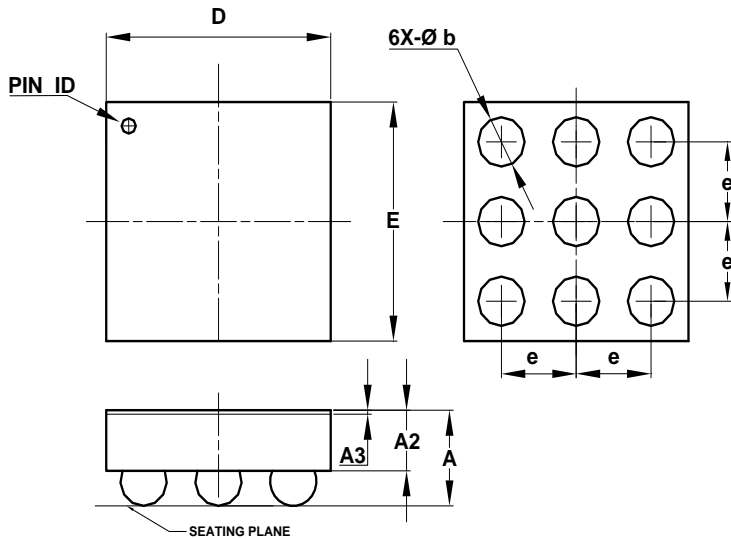


Fig. 10 Transient Thermal Resistance

Package Outline Dimensions

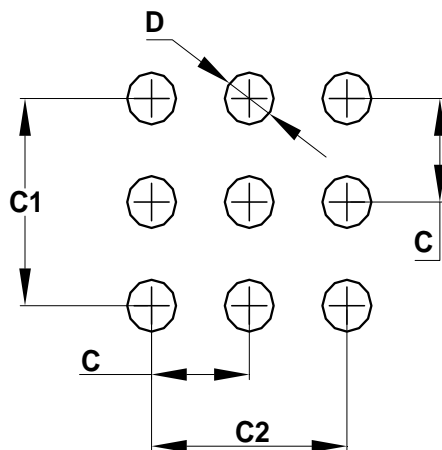
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



U-WLB1515-9			
Dim	Min	Max	Typ
A	-	0.62	-
A2	-	0.36	0.36
A3	0.020	0.030	0.025
b	0.27	0.37	0.32
D	1.47	1.51	1.49
E	1.47	1.51	1.49
e	-	-	0.50
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.50
C1	1.00
C2	1.00
D	0.25

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